

TECHNICAL DATA SHEET

BONDAN SE05

Revision: 19.03.2021
Version: 1.003



PRODUCT DESCRIPTION

BONDAN SE05 is a fast-curing adhesive with a medium viscosity. It is temperature-resistant up to approx. 80 °C and is suitable for bonding various materials such as many kinds of plastics, metals or wood.

The product exhibits a slightly delayed curing which enables corrections during assembly.

TECHNICAL PROPERTIES

Appearance	liquid
Color	transparent
Chemical basis	ethyl cyanoacrylate
Viscosity at 25 °C	1800 – 2200 mPa·s
Density at 25 °C	≈ 1.06 g/cm ³
Tensile strength (ASTM D412)	
Neoprene	5 – 15 N/mm ²
Nitrile rubber	5 – 15 N/mm ²
EPDM	2 – 6 N/mm ²
Lap shear strength (ISO 4587)	
Steel	15 – 25 N/mm ²
Aluminium	7 – 10 N/mm ²
ABS	6 – 10 N/mm ²
Polycarbonate (PC)	5 – 10 N/mm ²
Nitrile rubber (referring to ISO 4587)	5 – 10 N/mm ²

Curing time in seconds at 22 ° C and 50% relative humidity (time until a tensile strength of 0.1 N/mm² is reached):

Plastics					Wood	Metals	
EPDM	Neoprene	Nitrile rubber	ABS	PC	Balsa	Steel	Aluminium
< 7	< 7	< 5	10 - 15	10 - 30	< 5	30 - 45	25 - 35

The curing time is particularly influenced by the relative humidity, material pairing, temperature, gap and substrate surface. In the case of materials that are difficult to bond, such as PE, PP, silicone, etc., we recommend pretreating the substrate with our primer BONDAN PR77.

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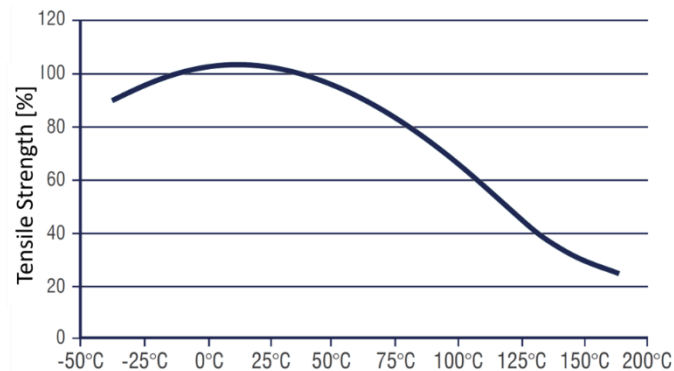
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TENSILE STRENGTH

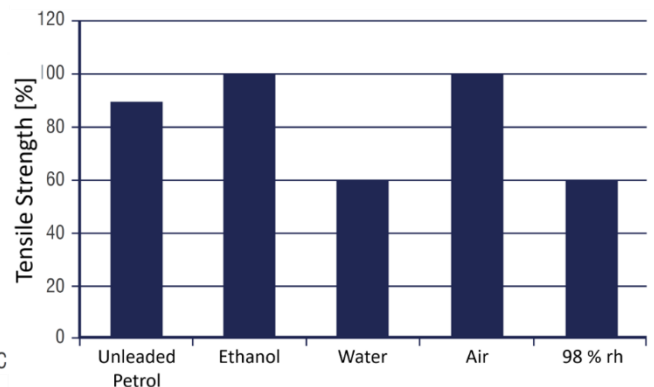
Temperature Resistance

Tested on steel, cured for 24 h and conditioned to test temperature for 1 h prior to testing.



Chemical Resistance

Exposure to the described conditions for 1000 h at 22 °C, except for 98 % relative humidity (rh) which was exposed at 42 °C.



DIRECTIONS FOR USE

- Please consult the safety data sheet before use.
- Clean, dry and grease-free surfaces ensure the maximum strength.
- Soiled surfaces must be cleaned (e.g. with BONDAN Cleaner or an appropriate solvent).
- Ensure sufficient flash-off time when cleaning parts.
- The curing time is especially influenced by the relative humidity, curing temperature, gap, substrate surface and material pairing.
- Dismantling and removal of adhesive residues can be facilitated by heating to 250 °C.

STORAGE

- 12 months at 2 to 10 °C in unopened packaging
- Do not store above 25 °C
- Store opened packaging in the refrigerator at 2 to 10 °C

PRODUCT LABELLING

See safety data sheet.

PACKAGE UNITS

- For manual application 20 g, 50 g, 500 g

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